

N32H785

Product Brief

The N32H785 series uses an ARM Cortex-M7 core, running at frequencies up to 600MHz, supporting double-precision floating-point operations and DSP instructions. It features (2/4MB) on-chip FLASH, integrates up to 1504KB of SRAM (including 1024KB TCM SRAM and 480KB SRAM) + 4KB Backup SRAM. It includes 3 12-bit 5Msps ADCs, 4 high-speed comparators, 6 12-bit DACs, and integrates multiple high-speed communication interfaces: U(S)ART, I2C, xSPI, SPI, USBHS Dual Role, CAN-FD, SDRAM, FEMC, SDMMC, and 10/100/1000M Ethernet.

The series supports digital camera interface (DVP), TFT-LCD graphical interface, JPEG hardware codec and GPU. It features a built-in high-performance encryption algorithm hardware acceleration engine, supporting AES/TDES, SHA, SM4 algorithms, TRNG true random number generator, and CRC8/16/32. It supports up to 126 GPIOs, and is available in LQFP176, BGA176+25 and BGA240+25 packages.

Key Features

- **Dual-core Architecture CPU (Cortex-M7 and Cortex-M4F)**
 - ARM Cortex-M7
 - 32-bit ARM Cortex-M7 core with a double-precision floating-point unit, supporting DSP instructions and MPU
 - Built-in 32 KB instruction Cache and 32 KB data Cache with ECC
 - Maximum operating frequency of 600 MHz, delivering 1284 DMIPS
 - ARM Cortex-M4F
 - 32-bit ARM Cortex-M4F core with FPU, featuring single-cycle hardware multiplication and division instructions, and supporting DSP instructions and MPU
 - Built-in 16 KB instruction Cache and 16 KB data Cache with parity check, supporting zero-wait execution of programs via the Flash accelerator unit
 - Maximum operating frequency of 300 MHz, delivering 375 DMIPS
- **Encrypted Memory**
 - On-chip Flash (2/4MB), supports encrypted storage and automatic program decryption during execution
 - 1504KB built-in SRAM, supports ECC verification
 - 1024KB TCM SRAM, configurable as D-TCM, I-TCM or SRAM
 - 480KB on-chip SRAM
 - 4KB Backup SRAM, supports ECC
- **Operating Modes**
 - Run mode
 - SLEEP mode: AXI enabled, AHB enabled
 - Stop0 mode: SRAM, TCM, RTC, LSE, IWDG enabled

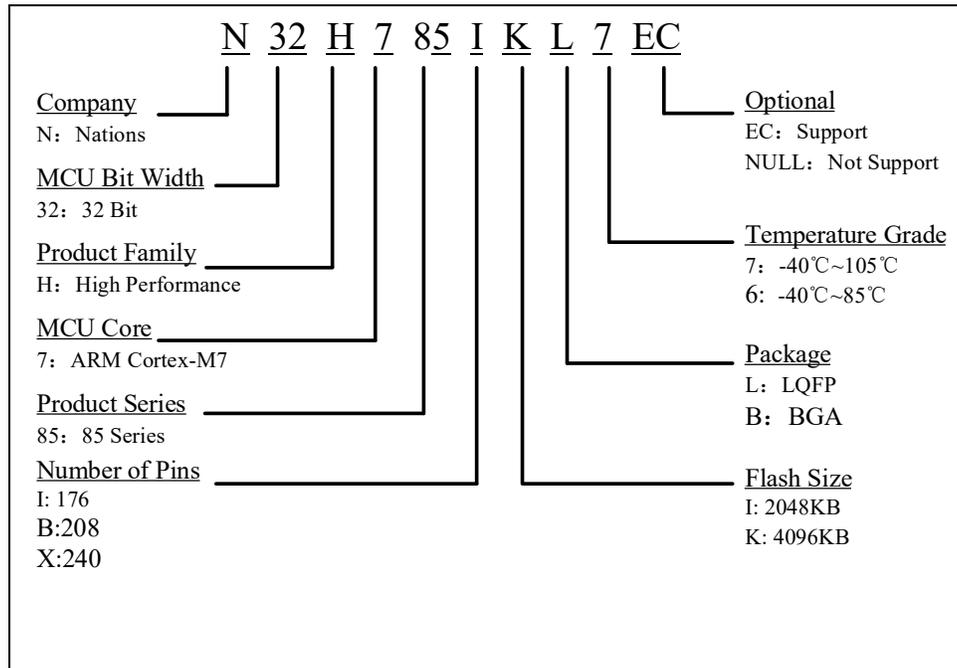
- Stop2 mode: Flash standby mode, SRAM, TCM, RTC, LSE, IWDG, Backup SRAM, backup registers enabled, I/O maintained
- Standby mode: Backup SRAM, RTC, IWDG, LSE, backup registers enabled, SRAM, TCM disabled
- VBAT mode: Backup SRAM, RTC, LSE, backup registers enabled
- **Clock**
 - 4MHz~48MHz external high-speed crystal
 - 4MHz~50MHz external clock input
 - 32.768KHz external low-speed crystal
 - Built-in 3 high-speed PLLs
 - Built-in MSI clock, supporting configuration of 31.25K/62.5K/125K/250K/500K/1M/2M/4M/8M/16MHz clocks
 - Internal high-speed RC 64MHz
 - Internal low-speed RC 32KHz
- **Reset**
 - Supports power-on/power-down/external pin reset
 - Supports watchdog reset and software system reset
 - Supports programmable voltage detection
- **High-Speed Communication Interfaces**
 - 8 USART interfaces/7 UART interfaces, supporting ISO7816, IrDA, LIN
 - 2 LPUART interfaces
 - 7 SPI interfaces, supporting master/slave modes, rates up to 50 MHz
 - 10 I2C interfaces, rates up to 3.4 MHz, configurable master/slave modes, dual address response in slave mode
 - 2 USBHS Dual Role interfaces
 - 8 CAN-FD bus interfaces
 - 2 Ethernet MAC interface, ETH1 supports 10M/100M/1000M communication rates, ETH2 supports 10M/100M communication rates . Supports IEEE 1588 time synchronization protocol
- **High-Performance Analog Interfaces**
 - 3 12-bit 5Msps ADCs, supporting 12-bit, 10-bit resolution, hardware oversampling up to 16-bit, supporting single-ended and differential modes
 - 4 high-speed analog comparators
 - 6 12-bit DACs, of which 2 1Msps DACs support output with or without Buffer separately, internal output only supports mode without Buffer; simultaneous internal and external output must enable Buffer; the other 2 DACs only support 1 output channel to the internal chip, with 15Msps sampling rate, supporting internal output without Buffer
 - 2 MCO outputs, configurable to output SYSCLK, HSE, MSI, LSE, LSI, HSI64 or PLL clock division
 - Supports 1 reference voltage VREFBUF (configurable as 1.5V/1.8V/2.048V/2.5V)
 - 1 temperature sensor

- **Audio Interfaces**
 - 4 I2S, supporting master/slave modes, audio sampling frequencies from 8KHz to 192KHz
 - 8 PDM digital microphone interfaces built into DSMU
- **Memory Extension Interfaces**
 - 1 FEMC (Flexible External Memory Controller) interface, bus rate 100 MHz, SRAM/PSRAM/Nor Flash supporting configurable 16/32-bit data width, NAND Flash supporting configurable 8/16-bit data width
 - 1 xSPI interface, supporting 1/2/4/8-bit data width, configurable master/slave, rates up to 133 MHz, can be used for external SRAM, PSRAM and Flash, supports XIP
 - 1 SDRAM interface, rates up to 133 MHz
 - 2 SDMMC interfaces, supporting SD/SDIO 3.0, eMMC 4.51 format, rates up to 104MHz
- **Image Processing Interfaces**
 - 2 digital camera interface (DVP), supporting 8/10/12/16bit, rates up to 110MHz
 - 1 TFT-LCD display interface, supporting up to 24-bit parallel digital RGB LCD, providing all signal interfaces, can directly connect to various LCD and TFT panels, resolution up to 1920x1080
 - Built-in 2.5D graphics processor, supporting image scaling, rotation, blending, anti-aliasing, texture mapping, etc.
 - Hardware JPEG codec
- **Maximum support for 168 GPIOs, low-speed GPIOs support 5V tolerance (under VDD = 3.3V ±10% conditions)**
- **Motor control Cordic accelerator, supporting trigonometric and hyperbolic function acceleration, supporting floating-point input and output**
- **Delta Sigma Module Unit (DSMU)**
- **Built-in filtering algorithm accelerator FMAC, supporting FIR, IIR filtering**
- **3 high-speed DMA controllers, each controller supporting 8 channels, 1 MDMA supporting 16 channels, freely configurable channel source and destination addresses**
- **RTC real-time clock, supporting leap year perpetual calendar, alarm events, periodic wake-up, supporting internal and external clock calibration**
- **Timer Counters**
 - 2 16bit super high-resolution timer (SHRTIM1/ SHRTIM2). Supports maximum control precision of 100ps, Each super high-resolution timer counter consists of 1 master timer unit and 6 16-bit slave timer units. each timer unit has 2 independent channels. Supports 12 independent PWM outputs or 6 pairs of complementary PWM outputs.
 - 4 16-bit advanced timer counters(ATIM1~4), supporting input capture, complementary output, quadrature encoding input and other functions, highest control precision 3.3ns; each timer has 6 independent channels, of which 4 channels support 4 pairs of complementary PWM outputs

- 10 16-bit general-purpose timers (GTIMA1~GTIMA7, GTIMB1~ GTIMB3), each timer with 4 independent channels, supporting input capture, output compare, PWM generation
- 4 32-bit basic timer counters (BTIM1~4)
- 5 16-bit low-power timers (LPTIM1~5), can work in Stop2 mode
- 2x 24-bit SysTick, 2x 14-bit window watchdog (WWDG), 2x 12-bit independent watchdog (IWDG)
- **Programming Methods**
 - Supports SWD/JTAG online debugging interface
 - Supports USB, USART Bootloader
- **Security Features**
 - FLASH has up to 4 encryption partitions, supporting storage encryption
 - Supports write protection (WRP), multiple levels of read protection (RDP) (L0/L1/L2)
 - Built-in password algorithm hardware acceleration engine, supporting AES/TDES, SHA, algorithms
 - TRNG true random number generator, CRC8/16/32 operations
 - Supports secure boot, encrypted program download, secure update, supports external high-speed and low-speed clock failure detection
 - Supports tamper detection
- **OTP supports 128-bit UCID**
- **Operating Conditions**
 - Operating voltage range:
 - 2.3V~3.6V
 - Chip junction temperature range: -40°C~125°C
- **Security Features**
 - USB IF
 - IEC61508 SIL2
- **Security Features**
 - LQFP176(24mm x 24mm)
 - BGA176+25(10mm x 10mm)
 - BGA240+25(14mm x 14mm)
- **Ordering Models**

Series	Models
N32H785xxx7	N32H785IKL7, N32H785IIL7, N32H785IKB7, N32H785IIB7, N32H785XKB7, N32H785XIB7

1 Naming Convention



2 Device Overview

Table 2-1 N32H785 Series Resource Configuration

Device Model		N32H785IKL7	N32H785IIL7	N32H785IKB7	N32H785IIB7	N32H785XKB7	N32H785XIB7
Flash (KB)		4096	2048	4096	2048	4096	2048
SRAM (KB)	TCM	1024 ⁽¹⁾					
	System RAM	480					
	Backup RAM	4					
Core	M7	600MHz					
	M4	300MHz					
Operating Voltage		2.3V~3.6V					
DCDC (step-down)		Yes					
Co-processor	Cordic	Yes					
	DSMU	Yes					
	FMAC	Yes					
Timers	SHRTIM	2					
	ADTIM	3 ⁽²⁾				4	
	GPTIM	10					
	BSTIM	4					
	LPTIM	5					
	SysTick timer	2					
	WWDG	2*14bit					
	IWDG	2*12bit					
RTC		Yes					
Communication Interfaces	SPI/I2S	6/4 ⁽³⁾				7/4	
	I2C	8 ⁽⁴⁾				10	
	USART	7 ⁽⁵⁾				8	
	UART	6 ⁽⁶⁾				7	
	LPUART	2					
	USBHS Dual Role	2					
	CAN FD	8 ⁽⁷⁾					
	10/100M ETH	2 ⁽⁸⁾					
	10/100/1000M ETH	1 ⁽⁸⁾					
Extended memory	SDRAM	Yes					
	xSPI	1 ⁽⁹⁾					
	FEMC	Yes					
	SDMMC	2					
Analog	12bit ADC Number of channels	3	28	3	36	3	43
	12bit DAC Number of channels	2+4 ⁽¹⁰⁾ 2 External channels					
	Comparators	4					

	VREFBUF	Yes		
Imaging	LCDC	Yes		
	GPU	Yes		
	JPEG	Yes		
	DVP	2		
	GPIO	121	126	168
DMA Number of channels	3 24Channel			
MDMA Number of channels	1 16Channel			
Algorithm support	DES/3DES, AES, SHA1/SHA224/SHA256, CRC8/16/CRC32			
Security Protection	Read/write protection (RDP/WRP), storage encryption, secure boot			
Packages	LQFP176 (24mm x 24mm)	BGA176+25 (10mm x 10mm)	BGA240+25 (14mm x 14mm)	

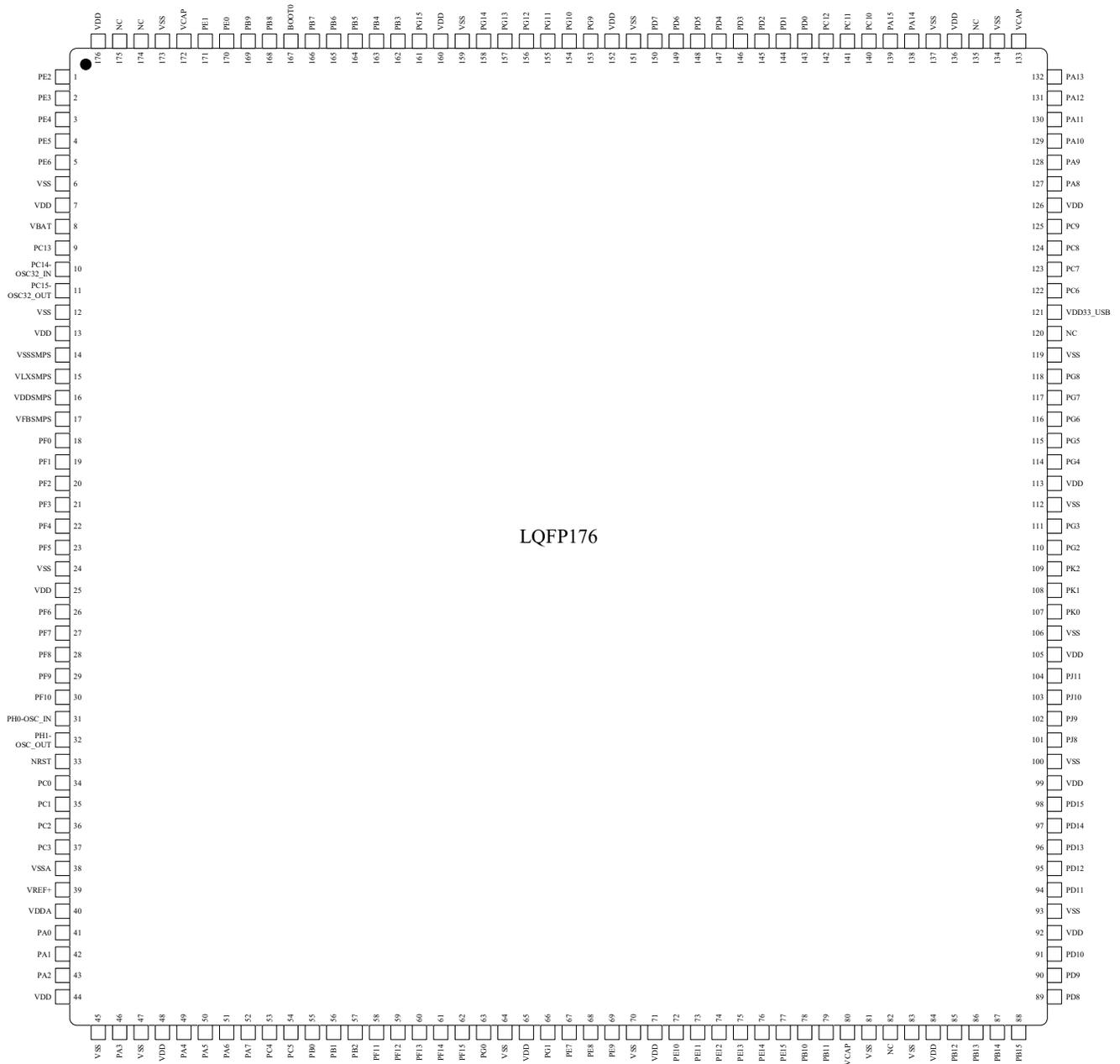
Note:

1. SRAM is the default memory upon power-on, and users can independently configure the size allocation of ITCM, DTCM and SRAM.
2. ATIM interfaces: ATIM1~3
3. SPI interfaces: SPI1~6; I2S interfaces: I2S1~4
4. I2C interfaces: I2C1~8
5. USART interfaces: USART1~7
6. UART interfaces: UART9~14
7. FDCAN interfaces: FDCAN1~8
8. ETH1 supports 10M/100M/1000M; ETH2 supports 10M/100M
9. xSPI interface: xSPI2
10. The 4 DACs only support internal connection and cannot output to GPIOs.

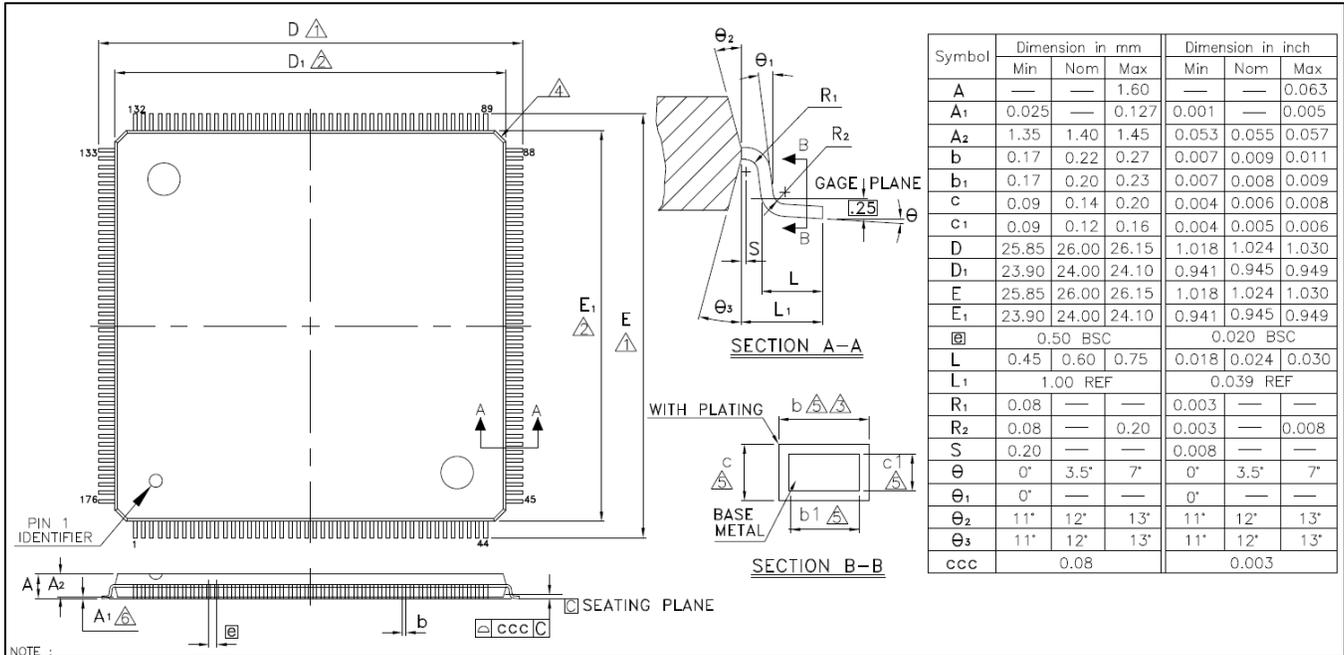
3 Package Information

3.1 LQFP176 Package

3.1.1 LQFP176 Pin Distribution

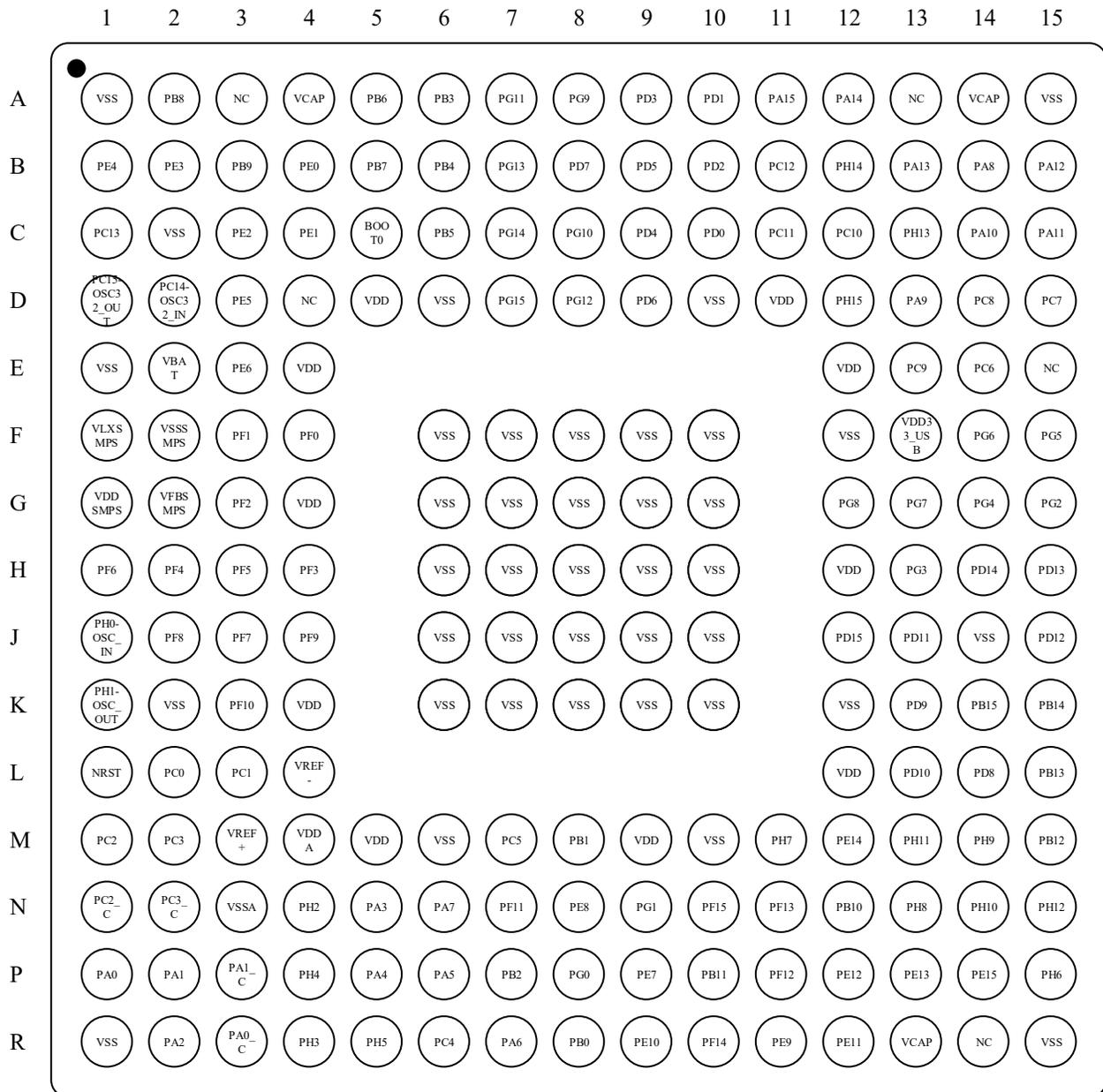


3.1.2 LQFP176 Package Size

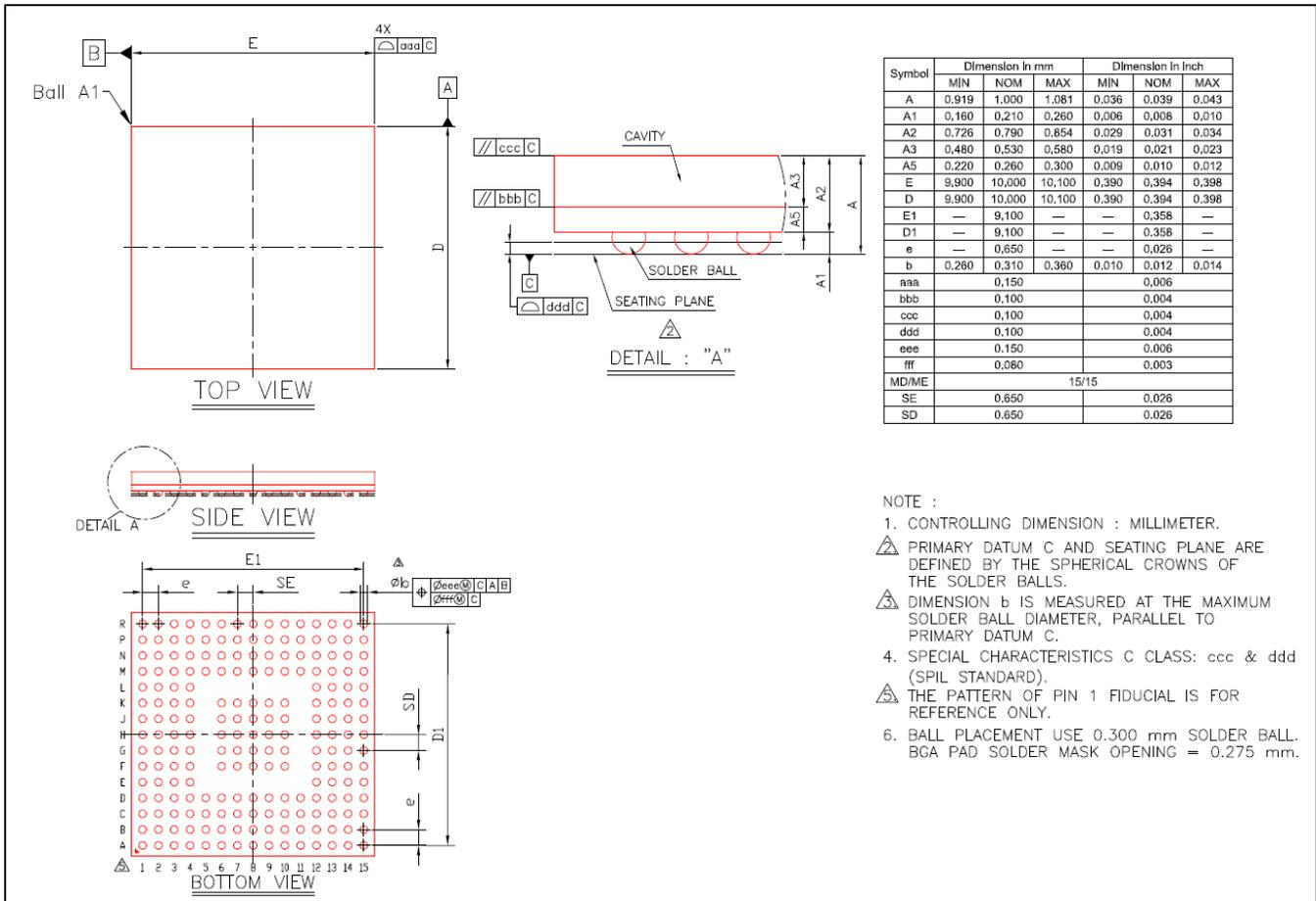


3.2 BGA176+25 Package

3.2.1 BGA176+25 Pin Distribution



3.2.2 BGA176+25 Package Size

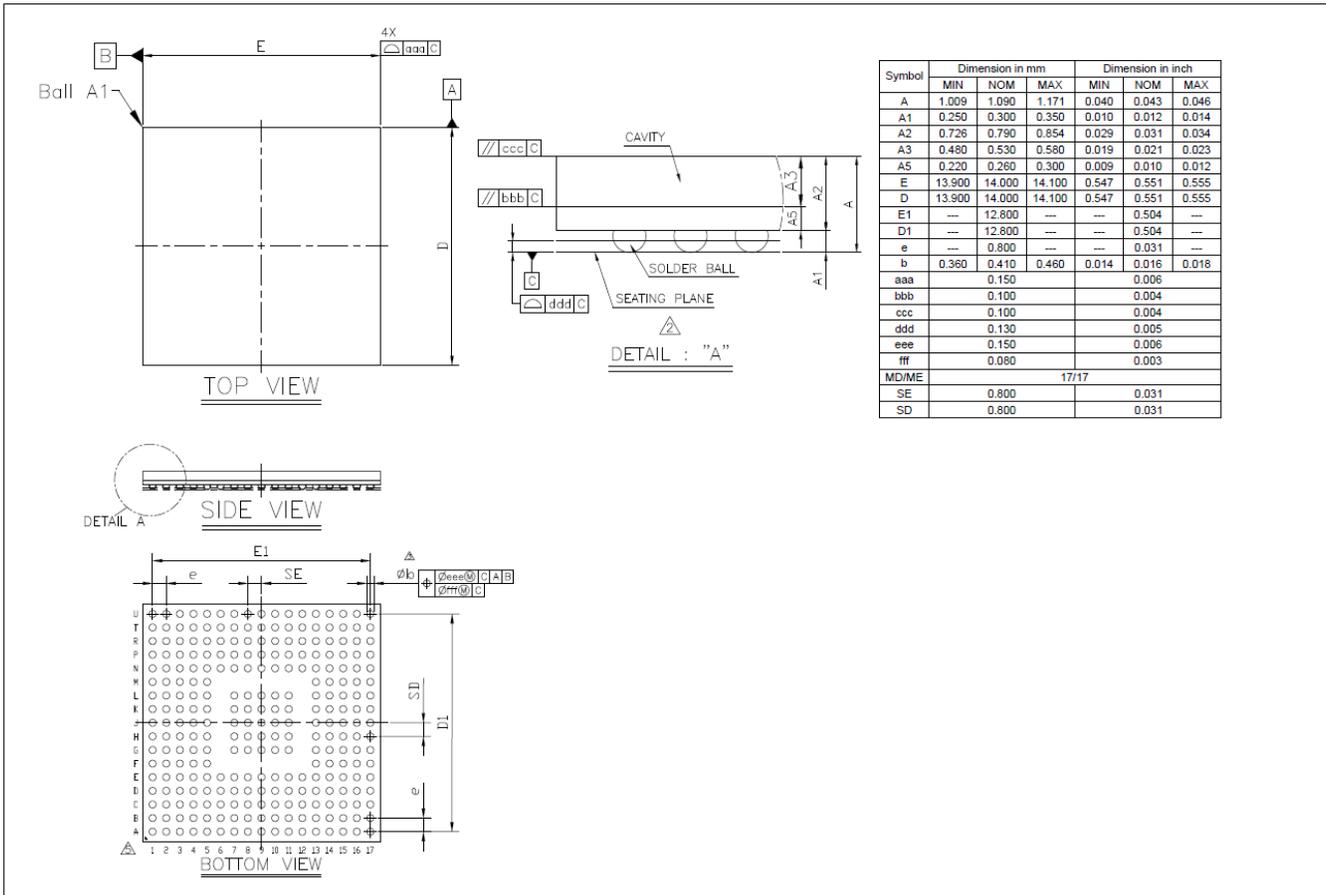


3.3 BGA240+25 Package

3.3.1 BGA240+25 Pin Distribution

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	
A	VSS	PI6	PI5	PI4	PB5	NC	VCAP	PK5	PG10	PG9	PD5	PD4	PC10	PA15	PI1	PI0	VSS	
B	VBA T	VSS	PI7	PE1	PB6	VSS	PB4	PK4	PG11	PJ15	PD6	PD3	PC11	PA14	PI2	PH15	PH14	
C	PC13 OSC3 2_OUT	PC14 OSC3 2_IN	PE2	PE0	PB7	PB3	PK6	PK3	PG12	VSS	PD7	PC12	VSS	PI3	PA13	VSS	NC	
D	PE5	PE4	PE3	PB9	PB8	PG15	PK7	PG14	PG13	PJ14	PJ12	PD2	PD0	PA10	PA9	PH13	VCAP	
E	VLXS MPS	PI9	PC13	PI8	PE6	VDD	NC	BOOT T0	VDD	PJ13	VDD	PD1	PC8	PC9	PA8	PA12	PA11	
F	VDD SMP5	VSS5 MPS	PI10	PI11	VDD								PC7	PC6	PG8	PG7	VDD3 3_US B	
G	PF2	VFBS MPS	PF1	PF0	VDD		VSS	VSS	VSS	VSS	VSS		VDD	PG5	PG6	VSS	NC	
H	PH12	PH13	PH14	PF3	VDD		VSS	VSS	VSS	VSS	VSS		VDD	PG4	PG3	PG2	PK2	
J	PH1- OSC OUT	PH0- OSC IN	VSS	PF5	PF4		VSS	VSS	VSS	VSS	VSS		VDD	PK0	PK1	VSS	VSS	
K	NRST	PF6	PF7	PF8	VDD		VSS	VSS	VSS	VSS	VSS		VDD	PJ11	VSS	NC	NC	
L	VDD A	PC0	PF10	PF9	VDD		VSS	VSS	VSS	VSS	VSS		VDD	PJ10	VSS	NC	NC	
M	VREF +	PC1	PC2	PC3	VDD								VDD	PJ9	VSS	NC	NC	
N	VREF -	PH2	PA2	PA1	PA0	PJ0	VDD	VDD	PE10	VDD	VDD	VDD	VDD	PJ8	PJ7	PJ6	VSS	NC
P	VSSA	PH3	PH4	PH5	PH15	PJ1	PF13	PF14	PE9	PE11	PB10	PB11	PH10	PH11	PD15	PD14	VDD	
R	PC2_ C	PC3_ C	PA6	VSS	PA7	PB2	PF12	VSS	PF15	PE12	PE15	PJ5	PH9	PH12	PD11	PD12	PD13	
T	PA0_ C	PA1_ C	PA5	PC4	PB1	PJ2	PF11	PG0	PE8	PE13	PH6	VSS	PH8	PB12	PB15	PD10	PD9	
U	VSS	PA3	PA4	PC5	PB0	PJ3	PJ4	PG1	PE7	PE14	VCAP	NC	PH7	PB13	PB14	PD8	VSS	

3.3.2 BGA240+25 Package Size



4 Version History

Version	Date	Changes
V1.1.0	2025.10.17	First release

5 Notice

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